Part Number Customer						
Category	Parameter		Specification	Measurement Method		
OverallWafer	1.0	Diameter	150.00 +/- 0.30 mm			
	2.0	Primary Flat Orientation	{110}+/-0.5 degree	Wafer Vendor		
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor		
	4.0	Secondary Flat Orientation	none			
	5.0	Overall Thickness	802.00 +/- 5.00 μm	ADE, 100%		
	6.0	Total Thickness Variation (TTV)	<3.00µm	Guaranteed by Process		
	7.0	Bow	<60.00µm	ADE to ASTM F534, 20%		
	8.0	Warp	<60.00µm	ADE to ASTM F657, 20%		
	9.0	Edge Chips	0	Bright Light, 100% (note 2)		
	10.0	Edge Exclusion	3mm			
HandleSilicon	11.0	Handle Growth Method	CZ	Wafer Vendor		
	12.0	Handle Orientation	{100} +/- 0.5 degree	Wafer Vendor		
	13.0	Handle Thickness	400.00 +/- 3.00 μm	ADE, 100%		
	14.0	Handle Doping Type	N	Wafer Vendor		
	15.0	Handle Dopant	Phosphorous	Wafer Vendor		
	16.0	Handle Resistivity	$1 \sim 10$ Ohmcm	Wafer Vendor		
	17.0	Handle Oxygen Concentration	<12.60ppma	Wafer vendor		
	18.0	Backside Finish	Polished with lasermark and oxide. Light handling marks.	Guaranteed by process		
BuriedOxide	19.0	Oxide Type	Thermal			
	20.0	Oxide Thickness	20,000.00 +/- 1,000.00 A	Nanospec centre point, 4%		
	21.0	Oxide formed on	Handle and/or Device Wafer			
DeviceSilicon	22.0	Device Growth Method	CZ	Wafer Vendor		
	23.0	Device Orientation	{100} +/- 0.5 degree	Wafer Vendor		
	24.0	Nominal Thickness	400.00 +/- 1.00 μm	ADE Single point, 100%		
	25.0	Distance to device silicon edge from wafer edge	<= 2.0mm	Typical by process		
	26.0	Device Doping Type	Ν	Wafer Vendor		
	27.0	Device Dopant	Phosphorous	Wafer Vendor		
	28.0	Device Resistivity	1 ~ 10 Ohmcm	Wafer Vendor		
	29.0	Oxygen Concentration	<12.60ppma	Wafer Supplier		
	30.0	Voids	All wafers scanned for voids by Scanning Acoustic Microscope (SAM)	SAM & Bright Light, 100% (note 2)		
	31.0	Scratches	0	Bright Light, 100% (note 2)		
	32.0	Haze	none	Bright Light, 100% (note 2)		

Icemos Technology Ltd

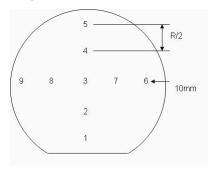
Product Specification

1000.528301

Part Number		Customer		
Category	Parameter	Specification	Measurement Method	
Shipping Details	Wafer per box :	Max 25		
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness		
Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.			

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information